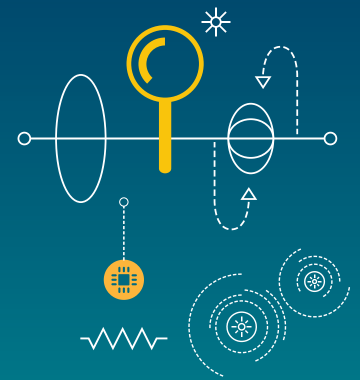


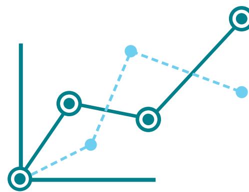
MDM9207-1 Delivering LTE to the Internet of Everything.

New LTE Cat 1 chipset solution offers scalable, cost-optimized, global connectivity.

Qualcomm Technologies, Inc. (QTI) continues to lead the IoT revolution with a newly expanded chipset portfolio. The MDM9207-1 offers device makers, system integrators, and developers a commercially proven chipset platform with industry-leading 3G/4G LTE multimode and multiband support, designed to bring reliable cellular connectivity on major network carriers worldwide. With Category 1 support, power and throughput optimization, and other customizable features, the MDM9207-1 connects a growing array of devices and systems within the Internet of Things. It's all in a highly integrated package engineered with scalability across the chipset platform to reduce bill-of-materials (BOM) costs, design complexity, and integration time.

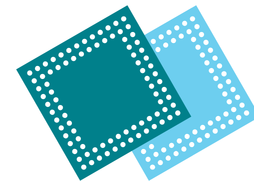
Purpose-built for the Internet of Things

While many mobile applications today require fast data speeds and high bandwidth, many IoT/M2M applications do not. Instead, these machine-to-machine-based applications require low bandwidth, low power, and long battery life, in a compact form factor at a cost-effective LTE price point. The MDM9207-1 was designed to meet that need, with proven modem core technology, support for Cat 1 with Power Save Mode (PSM), built-in hardware and software security features, and the longevity M2M devices require.



Optimized for cost and simplicity

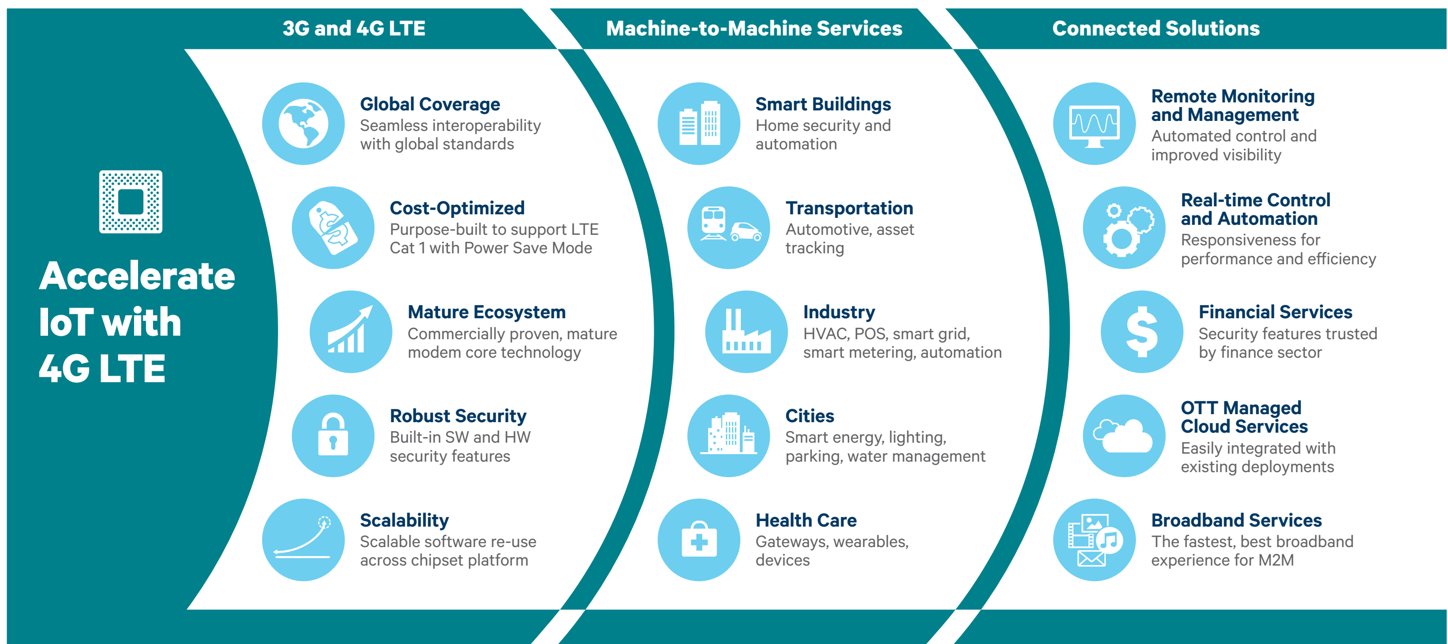
QTI's MDM9207-1 is a cost-optimized IoT solution with a number of integrated features designed to reduce overall BOM and NRE costs for our customers. These include an ARM Cortex-A7 AP that minimizes the need for discrete MCUs and a discrete GNSS for location services, and scalable software reuse across the chipset platform that reduces design complexity, eases development costs and enables faster time to launch.



Flexible chipset platform

Offering seamless interoperability, worldwide capability and scale with global band support for all major cellular standards, the chipset platform also supports the major RF bands and band combinations. With integrated voice support for Circuit Switched Fall Back (CSFB) and VoLTE, the platform offers pre-integrated support to add Wi-Fi (1x1, 802.11ac) and BT 4.1 BLE. Developers can also access a robust software development environment with the Linux OS platform. The chipset platform also enables development of solutions targeting a specific geography or vertical—with the potential to enable a single worldwide SKU.

Tomorrow's top-to-bottom solution, built today



Customizable features include support for:

- LTE Category 1 up to 10 Mbps downlink and up to 5 Mbps uplink speeds with LTE multimode or LTE single-mode capability and dual Rx or single Rx
- Power Save Mode (PSM) enabling 10+ years of battery life
- Major cellular standards, including LTE FDD, LTE TDD, DC-HSPA, GSM and TD-SCDMA
- Scalable software across chipset platforms
- Advanced, built-in hardware and software security features
- Integrated voice support for Circuit Switched Fall Back (CSFB) and VoLTE
- Integrated Applications Processor with ARM Cortex-A7 AP at 1.2 GHz
- Linux OS for application development
- Integrated global positioning support for GPS, Beidou, GLONASS, and Galileo
- Small package at 28nm LP to allow for optimized IoT form factors
- Pre-integrated support for Qualcomm® VIVE™ Wi-Fi 1x1, 802.11ac featuring Qualcomm® MU | EFX MU-MIMO technology and BT 4.1 BLE
- Qualcomm RF360™ Front End Solution

Meeting new demands

By 2020, ~25 billion devices, machines, and things will be permanently connected to the cloud and each other.[1] A scalable, intelligent and converged connectivity fabric is required to handle the extreme variations and requirements of this new hyper-connected era. With our chipset expertise and connectivity capabilities, Qualcomm Technologies is creating a portfolio of innovative solutions to meet the challenges facing IoT/M2M industries today.

[1] Source: Machina Research; April 2013, IDC, March 2013; Gartner, September 2013

©2015 Qualcomm Technologies, Inc. All rights reserved. Qualcomm VIVE and Qualcomm MU | EFX are products of Qualcomm Atheros, Inc. Qualcomm RF360 is a product of Qualcomm Technologies, Inc.
Qualcomm RF360 and VIVE are trademarks of Qualcomm Incorporated, registered in the United States and other countries. Other product and brand names may be trademarks or registered trademarks of their respective owners.